L Numb r	Hits	S arch Text	DB	Tim stamp
1	2	("5918113").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/28 21:14
-	31	(("5013119") or ("1013002") or ("1084014") or ("1199930") or ("6283225") or ("916I544") or ("9293414") or ("1135567")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 20:15
-	23	"05013119" "01013002" "01084014" "01199930" "06283225" "0916I544" "09293414" "01135567"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 20:24
-	0	"0901615 <i>44</i> "	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/15 20:24
-	0	("9161544").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/15 20:25
-	0	("90161544").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/15 20:25
-	0	"090161544"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/15 20:25
-	0	"9161544"	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/15 20:25
-	0	("9161544").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/10/15 20:32
-	1	1993-062929.NRAN.	IBM_TDB DERWENT	2003/10/15 20:46

		r — — — — — — — — — — — — — — — — — — —		
-	2	"10013002"	USPAT;	2003/10/16
			US-PGPUB;	16:17
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	1998-136816.NRAN.	DERWENT	2003/10/15
				21:39
-	1	1993-062929.NRAN.	DERWENT	2003/10/15
				21:40
-	2	5013119.URPN.	USPAT	2003/10/15
				21:40
-	0	10013002.URPN.	USPAT	2003/10/15
				21:41
-	0	10013002.URPN.	USPAT	2003/10/15
				21:41
-	2835	metamorph\$	USPAT;	2003/10/16
			US-PGPUB;	16:17
1			EPO; JPO;	
			DERWENT;	
	007.555		IBM_TDB	
-	367133	ероху	USPAT;	2003/10/16
			US-PGPUB;	16:17
ļ			EPO; JPO;	į į
			DERWENT;	
			IBM_TDB	
-	3	metamorph\$ adj epoxy	USPAT;	2003/10/16
			US-PGPUB;	21:06
			EPO; JPO;	
1			DERWENT;	
	F6700	41.1.1	IBM_TDB	0000/40/40
-	56790	thickness near direction	USPAT;	2003/10/16
			US-PGPUB;	21:56
			EPO; JPO;	
			DERWENT;	
1_	0	"090306573"	_	2002/40/46
1 -	"	U9U3U0313	USPAT;	2003/10/16 21:56
			US-PGPUB;	£ 1:30
1			EPO; JPO; DERWENT;	
}			IBM_TDB	
1_	2	"09306573"	USPAT;	2003/10/16
			US-PGPUB;	22:03
	1		EPO; JPO;	
1			DERWENT;	
1	1		IBM_TDB	
_	1	1998-068875.NRAN.	DERWENT	2003/10/16
	•	Jood John Mill	PEKAAEIAI	21:57
_	2	"10199930"	USPAT;	2003/10/17
	-		US-PGPUB;	17:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
L			1	L

	1	1998-473136.NRAN.	DERWENT	2003/10/16
	•	1335-473 130.INCAR.	DERVER	22:03
-	0	10199930.URPN.	USPAT	2003/10/16
1			Ì	22:04
-	48513	elastic\$ near modulus	USPAT;	2003/10/17
			US-PGPUB;	17:44
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
] -	49722	cte (coefficient near thermal near	USPAT;	2003/10/17
	1	expansion)	US-PGPUB;	17:45
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
-	247456	(first second) adj2 layer	USPAT;	2003/10/17
			US-PGPUB;	17:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	139550	two adj layer	USPAT;	2003/10/17
			US-PGPUB;	17:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	302	438/188,119.ccls.	USPAT;	2003/10/17
			US-PGPUB;	17:45
			EPO; JPO;	
			DERWENT;	
	344248	((first second) adj2 layer) (two adj layer)	IBM_TDB	2003/10/17
-	344246	((III'st second) adj2 layer) (two adj layer)	USPAT; US-PGPUB;	17:47
			EPO; JPO;	17.47
			DERWENT;	
	1		IBM_TDB	
	118531	anisotrop\$	USPAT;	2003/10/17
			US-PGPUB;	1
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2901	(elastic\$ near modulus) and (cte	USPAT;	2003/10/17
		(coefficient near thermal near expansion))	US-PGPUB;	17:48
		,	EPO; JPO;	
}			DERWENT;	
			IBM_TDB	
-	344	anisotrop\$ and ((elastic\$ near modulus) and	USPAT;	2003/10/17
	1	(cte (coefficient near thermal near	US-PGPUB;	17:48
		expansion)))	EPO; JPO;	
	1		DERWENT;	
L			IBM_TDB	

	T		,	
	118	(((first s nd) adj2 layer) (two adj lay r)) and (anis tr p\$ and ((elastic\$ n ar modulus) and (cte (coeffici nt near thermal n ar expansion))))	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 17:48
-	0	438/188,119.ccis. and ((((first second) adj2 layer) (two adj layer)) and (anisotrop\$ and ((elastic\$ near modulus) and (cte (coefficient near thermal near expansion))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 17:48
-	1721521	semiconductor integrated adj circuit ic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 17:49
-	81	((((first second) adj2 layer) (two adj layer)) and (anisotrop\$ and ((elastic\$ near modulus) and (cte (coefficient near thermal near expansion))))) and (semiconductor integrated adj circuit ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 17:49
	4709545	@ad>19990217 @rlad>19990217 @pt1d>19990217	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 17:49
-	24	(((((first second) adj2 layer) (two adj layer)) and (anisotrop\$ and ((elastic\$ near modulus) and (cte (coefficient near thermal near expansion))))) and (semiconductor integrated adj circuit ic)) not (@ad>19990217 @rlad>19990217 @pt1d>19990217)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 20:31
-	527040	silica\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 17:50
-	6	silica\$ and ((((((first second) adj2 layer) (two adj layer)) and (anisotrop\$ and ((elastic\$ near modulus) and (cte (coefficient near thermal near expansion))))) and (semiconductor integrated adj circuit ic)) not (@ad>19990217 @rlad>19990217 @pt1d>19990217))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 17:50
•	35241	double adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 20:31

	27222	T	T	r
-	370236	(((first se ond) adj2 layer) (tw adj layer))	USPAT;	2003/10/17
		r (double adj layer)	US-PGPUB;	20:47
			EPO; JPO;	
			DERWENT;	
		0004	IBM_TDB	
-	1	ac8301	USPAT;	2003/10/17
			US-PGPUB;	20:48
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	5554	((((first second) adj2 layer) (two adj layer))	USPAT;	2003/10/17
		or (double adj layer)) with anisotrop\$	US-PGPUB;	20:48
			EPO; JPO;	
	İ		DERWENT;	
			IBM_TDB	
-	4319	(semiconductor integrated adj circuit ic)	USPAT;	2003/10/17
		and (((((first second) adj2 layer) (two adj	US-PGPUB;	20:48
		layer)) or (double adj layer)) with	EPO; JPO;	
		anisotrop\$)	DERWENT;	
			IBM_TDB	
-	2	((elastic\$ near modulus) and (cte	USPAT;	2003/10/17
		(coefficient near thermal near expansion)))	US-PGPUB;	20:59
		and ((semiconductor integrated adj circuit	EPO; JPO;	
		ic) and (((((first second) adj2 layer) (two adj	DERWENT;	
		layer)) or (double adj layer)) with	IBM_TDB	
		anisotrop\$))		
-	2	(((((first second) adj2 layer) (two adj layer))	USPAT;	2003/10/17
		or (double adj layer)) with anisotrop\$) and	US-PGPUB;	21:01
İ		((elastic\$ near modulus) and (cte	EPO; JPO;	
		(coefficient near thermal near expansion)))	DERWENT;	
			IBM_TDB	
-	56790	thickness near direction	USPAT;	2003/10/17
			US-PGPUB;	21:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1338	anisotrop\$ with (thickness near direction)	USPAT;	2003/10/17
			US-PGPUB;	21:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	210	(anisotrop\$ with (thickness near direction))	USPAT;	2003/10/17
		and ((((first second) adj2 layer) (two adj	US-PGPUB;	21:04
		layer)) or (double adj layer))	EPO; JPO;	
		• • •	DERWENT;	
			IBM_TDB	
-	111	((anisotrop\$ with (thickness near	USPAT;	2003/10/17
}	1	direction)) and ((((first second) adj2 layer)	US-PGPUB;	21:04
1		(tw adj layer)) r (double adj layer))) and	EPO; JPO;	
		(semic nduct rintegrated adj circuit ic)	DERWENT;	
	ļ	· · · · · · · · · · · · · · · · · · ·	IBM_TDB	
<u> </u>				L

•	57	(((anisotr p\$ with (thi kness n ar	U PAT;	2003/10/17
	1	directi n)) and ((((first sec nd) adj2 lay r)	US-PGPUB;	21:05
	1	(two adj lay r)) r (double adj layer))) and	EPO; JPO;	
		(s mic nduct rintegrated adj ircuit i))	DERWENT;	
		not (@ad>19990217 @rlad>19990217	IBM_TDB	
		@pt1d>19990217)		
-	7	(US-5120665-\$ or US-5001542-\$ or	USPAT	2003/10/17
		US-4977007-\$ or US-6172878-\$ or		21:44
		US-6042894-\$ or US-6034331-\$ or		
		US-5438223-\$).did.		
•	2486	underfil\$	USPAT	2003/10/17
				21:45
-	77	((elastic\$ near modulus) and (cte	USPAT	2003/10/17
	}	(coefficient near thermal near expansion)))		21:45
		and underfil\$		
-	37	(((elastic\$ near modulus) and (cte	USPAT	2003/10/17
		(coefficient near thermal near expansion)))		21:45
		and underfil\$) not (@ad>19990217		
		@rlad>19990217 @pt1d>19990217)		
•	3	"01135567"	USPAT;	2003/10/19
			US-PGPUB;	16:40
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	7	("1135567").PN.	USPAT;	2003/10/19
			US-PGPUB;	14:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	7	"1120449"	USPAT;	2003/10/19
			US-PGPUB;	16:44
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	7	("1120449").PN.	USPAT;	2003/10/19
			US-PGPUB;	16:44
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	